# MA2SD24

### Silicon epitaxial planar type

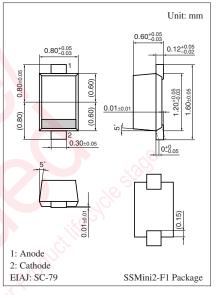
For super high speed switching

#### Features

- Forward current (Average)  $I_{F(AV)} = 200$  mA rectification is possible
- Small reverse current  $I_R$

Parameter	Symbol	Rating	Unit			
Reverse voltage	V <sub>R</sub>	20	v			
Repetitive peak reverse voltage	V <sub>RRM</sub>	20	V			
Peak forward current	I <sub>FM</sub>	300	mA			
Forward current (Average)	I <sub>F(AV)</sub>	200	mA			
Non-repetitive peak forward surge current *	I <sub>FSM</sub>	1	А			
Junction temperature	Tj	125	°C			
Storage temperature	T <sub>stg</sub>	-55 to +125	°C			





Marking Symbol: 5L

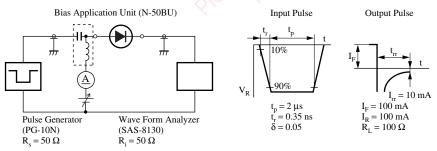
Note) \*: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V <sub>F</sub>	$I_F = 200 \text{ mA}$	10 <sup>-</sup>	0.50	0.58	V
Reverse current	IR	V <sub>R</sub> = 10 V		0.1	1.0	μΑ
Terminal capacitance	C <sub>t</sub>	$V_R = 0 V, f = 1 MHz$	$\sim 2^{\circ}$	25		pF
Reverse recovery time *	t <sub>rr</sub>	$I_{\rm F} = I_{\rm R} = 100 \text{ mA}$		3		ns
	SCO.	$I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$				

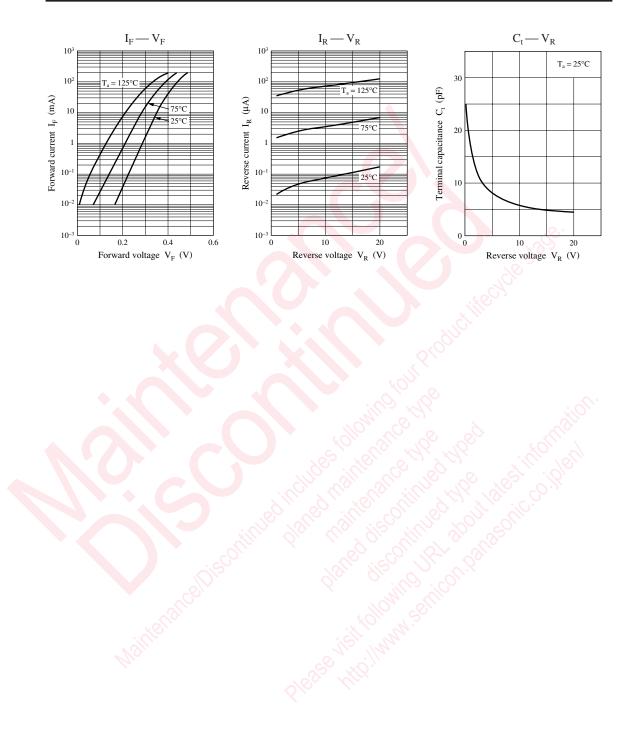
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 250 MHz.
- 4. \*: t<sub>rr</sub> measurement circuit



### MA2SD24

## Panasonic



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